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This listing of claims will replace all prior versions, and listings, of claims in the application:

## **LISTING OF CLAIMS:**

Claim 1 (canceled)

Claim 2 (currently amended): A conductor pattern according to Claim 1, wherein comprising:

a plurality of straight lines; and

a plurality of corners connected to the plurality of straight lines;

wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof;

a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines; and the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

Claim 3 (currently amended): A conductor pattern according to Claim 42, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

Claim 4 (currently amended): A conductor pattern according to Claim 1, wherein comprising:

a plurality of straight lines; and

a plurality of corners connected to the plurality of straight lines;

wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof;

a bottom surface cross-sectional width of each of the plurality of corners is larger

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than a bottom surface cross-sectional width of each of the plurality of straight lines; and the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

Claim 5 (currently amended): A conductor pattern according to Claim  $4\underline{2}$ , wherein the conductor pattern is made of photo-sensitive conductive paste.

Claim 6 (canceled)

Claim 7 (currently amended): An electronic component according to Claim 6, wherein comprising:

a substrate; and

at least one conductor pattern disposed on the substrate, the at least one conductor pattern including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines;

wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof;

a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines; and the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

Claim 8 (currently amended): An electronic component according to Claim 67, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

Claim 9 (currently amended): An electronic component according to Claim 6,

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## wherein comprising:

a substrate; and

at least one conductor pattern disposed on the substrate, the at least one conductor pattern including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines;

wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof;

a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines; and the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

Claim 10 (currently amended): An electronic component according to Claim 67, wherein the conductor pattern is made of photo-sensitive conductive paste.

Claim 11 (canceled)

Claim 12 (currently amended): The method according to claim 11, wherein A method of forming a conductor comprising the steps of:

forming a photo-sensitive conductive paste on a surface of a substrate;

exposing the photosensitive conductive paste;

developing the photosensitive conductive paste; and

burning the photo-sensitive conductive paste to produce a conductor including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-

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sectional width of each of the plurality of straight lines, and the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

Claim 13 (currently amended): The method according to claim 1112, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

Claim 14 (currently amended): The method according to claim 11, wherein A method of forming a conductor comprising the steps of:

forming a photo-sensitive conductive paste on a surface of a substrate; exposing the photosensitive conductive paste;

developing the photosensitive conductive paste; and

burning the photo-sensitive conductive paste to produce a conductor including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines, and the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

Claim 15 (canceled)

Claim 16 (canceled)

Claim 17 (currently amended): The method according to claim 16, wherein A method of forming an electronic component the steps of:

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providing a substrate;

forming at least one conductor on the substrate, the step of forming the at least one conductor including the steps of:

forming photo-sensitive conductive paste on a surface of a substrate;

exposing the photosensitive conductive paste;

developing the photosensitive conductive paste; and

burning the photo-sensitive conductive paste to produce a conductor including a plurality of straight lines and a plurality of corners connected to the plurality of straight lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines, and the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.07 times the conductor thickness of each of the plurality of corners.

Claim 18 (currently amended): The method according to claim 1617, wherein the bottom surface cross-sectional width of each of the plurality of corners is at least about 1.5 times the conductor thickness of each of the plurality of corners.

Claim 19 (currently amended): The method-according to claim 16, wherein A method of forming an electronic component the steps of:

providing a substrate;

forming at least one conductor on the substrate, the step of forming the at least one conductor including the steps of:

forming photo-sensitive conductive paste on a surface of a substrate;

exposing the photosensitive conductive paste;

developing the photosensitive conductive paste; and

burning the photo-sensitive conductive paste to produce a conductor including a

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plurality of straight lines and a plurality of corners connected to the plurality of straight lines, wherein a bottom surface cross-sectional width of the conductor pattern is not larger than a top surface cross-sectional width thereof, and a bottom surface cross-sectional width of each of the plurality of corners is larger than a bottom surface cross-sectional width of each of the plurality of straight lines, and the bottom surface cross-sectional width of each of the plurality of straight lines is at least about 0.67 times the conductor thickness of each of the plurality of straight lines.

Claim 20 (canceled)